## INFORMATION DISCLOSURE STATEMENT

Applicant : Todd et al.

App. No : 10/623,482

Filed : July 18, 2003

For : METHOD TO FORM ULTRA HIGH

QUALITY SILICON-CONTAINING

COMPOUND LAYERS

Examiner : Ron Everett Pompey

Art Unit : 2812

## Mail Stop Amendment

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing in the above-identified application is a PTO/SB/08 Equivalent listing 4 references to be considered by the Examiner. Also enclosed are 3 foreign patent references and/or non-patent literature as listed on the Information Disclosure Statement.

This Information Disclosure Statement is being filed within three months of the filing date, with an RCE or before receipt of a first office action after an RCE and no fee is required.

The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment, to Account No. 11-1410.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: 6/>/o>

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Zi Y. Wong / Registration No. 58,410

Attorney of Record Customer No. 20,995 (415) 954-4114

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## INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Multiple sheets used when necessary) Application Filing Date First Name Art Unit Examiner

SHEET 1 OF 1

| Application No.      | 10/623,482         |
|----------------------|--------------------|
| Filing Date          | July 18, 2003      |
| First Named Inventor | Michael A. Todd    |
| Art Unit             | 2812               |
| Examiner             | Ron Everett Pompey |
| Attorney Docket No.  | ASMEX.376A         |

| Ì |                      | U.S. PATENT DOCUMENTS |   |                                |                               |  |
|---|----------------------|-----------------------|---|--------------------------------|-------------------------------|--|
|   | Examiner<br>Initials | Cite<br>No.           | Document Number<br>Number - Kind Code (if known)<br>Example: 1,234,567 B1 | Publication Date<br>MM-DD-YYYY | Name of Patentee or Applicant | Pages, Columns, Lines Where<br>Relevant Passages or Relevant<br>Figures Appear |
| ı |                      | 1                     | 2001/032986 A1  | 10-25-2001                     | Miyasaka                      |  |

|                      | FOREIGN PATENT DOCUMENTS |  |                                   |   |  |                |
|----------------------|--------------------------|--|-----------------------------------|---|--|----------------|
| Examiner<br>Initials | Cite<br>No.              | Foreign Patent Document<br>Country Code-Number-Kind Code<br>Example: JP 1234567 A1 | Publication<br>Date<br>MM-DD-YYYY | Name of Patentee or<br>Applicant            | Pages, Columns, Lines<br>Where Relevant Passages or<br>Relevant Figures Appear | T <sup>1</sup> |
|                      | 2                        | GB 2 298 313 A   | 08-28-1996                        | Hyundai Electronics<br>Industries Co., Ltd. |  |                |
|                      | 3                        | WO 02/064853 A2  | 08-22-2002                        | ASM America, Inc.                           |  |                |

|                      | NON PATENT LITERATURE DOCUMENTS |  |                |
|----------------------|---------------------------------|--|----------------|
| Examiner<br>Initials | Cite<br>No.                     | Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the<br>item (book, magazine, bumans, serial, symposium, catalog, etc.), date, page(s), volume-issue<br>number(s), publisher, city and/or country where published. | T <sup>1</sup> |
|                      |                                 | International Search Report and Written Opinion for International Application No. PCT/US2006/047805. May 08, 2007  |                |

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Examiner Signature

Date Considered

\*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.